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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q62228

Yoshihisa FURUTA, et al.

Appln. No.: 09/719,422

Group Art Unit: 1733

Confirmation No.: 7788

Examiner: Barbara J. MUSSER

Filed: December 12, 2000

For: METHOD OF RESIN ENCAPSULATING SEMICONDUCTOR CHIP AND  
PRESSURE-SENSITIVE ADHESIVE TAPE FOR ADHESION TO LEADFRAME AND  
THE LIKE

**REQUEST FOR APPROVAL OF PROPOSED DRAWING CORRECTIONS**

Commissioner for Patents  
Washington, D.C. 20231

Sir:

Submitted herewith please find 2 sheets of proposed drawing corrections with the  
changes indicated in red ink. The Examiner is respectfully requested to acknowledge receipt of  
the drawing corrections and approve the changes.

Respectfully submitted,

Mark Boland  
Registration No. 32,197

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Date: October 7, 2002